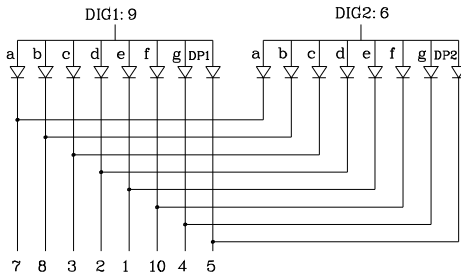
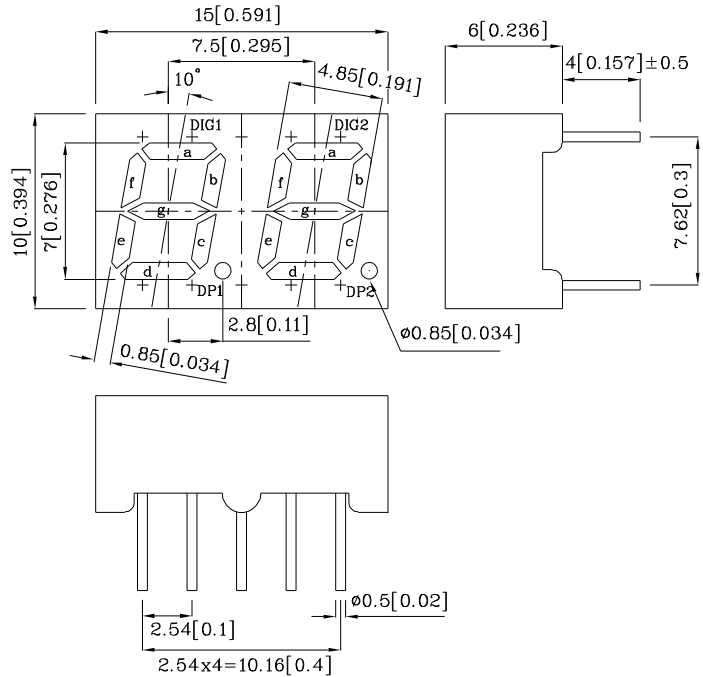


PRELIMINARY SPEC

**Features**

- 0.28 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- TWO DIGIT PACKAGE SIMPLIFIES ALIGNMENTS & ASSEMBLY.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, WHITE SEGMENT.
- RoHS COMPLIANT.



Notes:

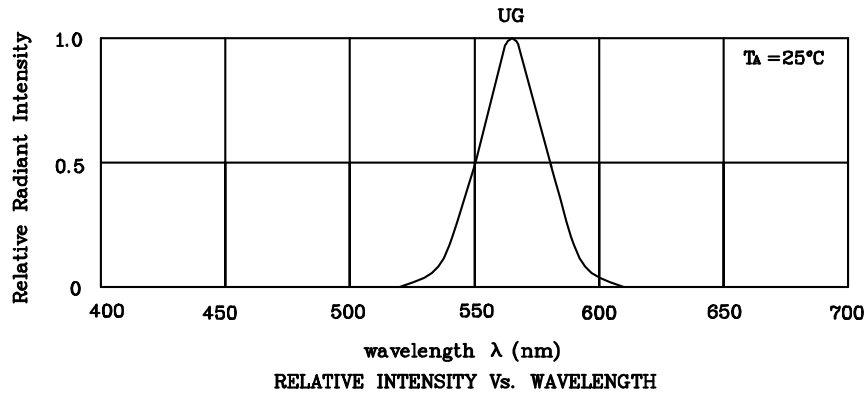
1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$ " unless otherwise noted.
3. Specifications are subject to change without notice.



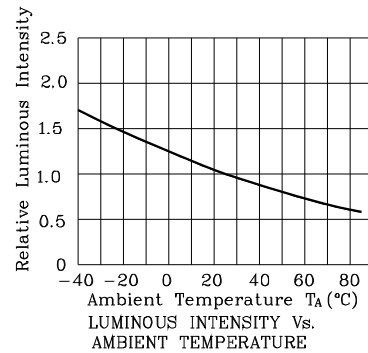
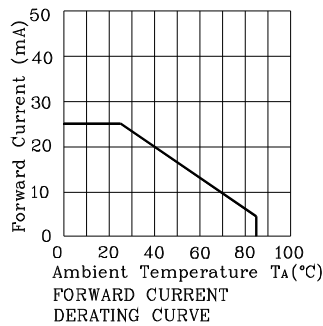
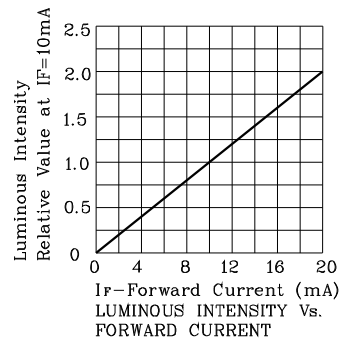
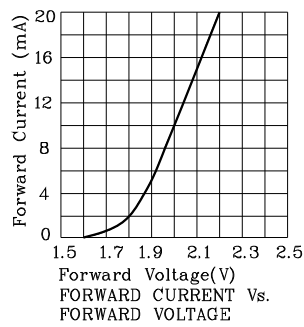
Absolute maximum ratings (TA=25°C)		UG (GaP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	140	mA
Power Dissipation	P <sub>T</sub>	62.5	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3~5 Seconds		

Operating Characteristics (T <sub>A</sub> =25°C)		UG (GaP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.0	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength of Peak Emission (Typ.) (I <sub>F</sub> =10mA)	λ <sub>p</sub>	565	nm
Wavelength of Dominant Emission (Typ.) (I <sub>F</sub> =10mA)	λ <sub>D</sub>	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	Δλ	30	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	15	pF

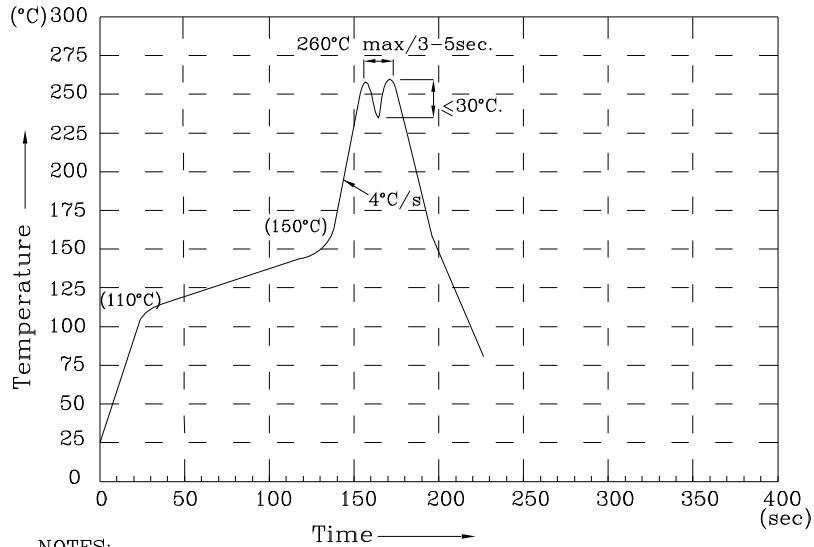
Part Number	Emitting Color	Emitting Material	Luminous Intensity (I <sub>F</sub> =10mA) ucd	Wavelength nm λ <sub>P</sub>	Description
			min.      typ.		
DUG07A2-1	Green	GaP	1200      6195	565	Common Anode, Rt. Hand Decimal
Published Date : MAR 04,2008		Drawing No : SDSA4542		V2	Checked : Shin Chi      P.1/4



❖ UG



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.No more than once.

Remarks:

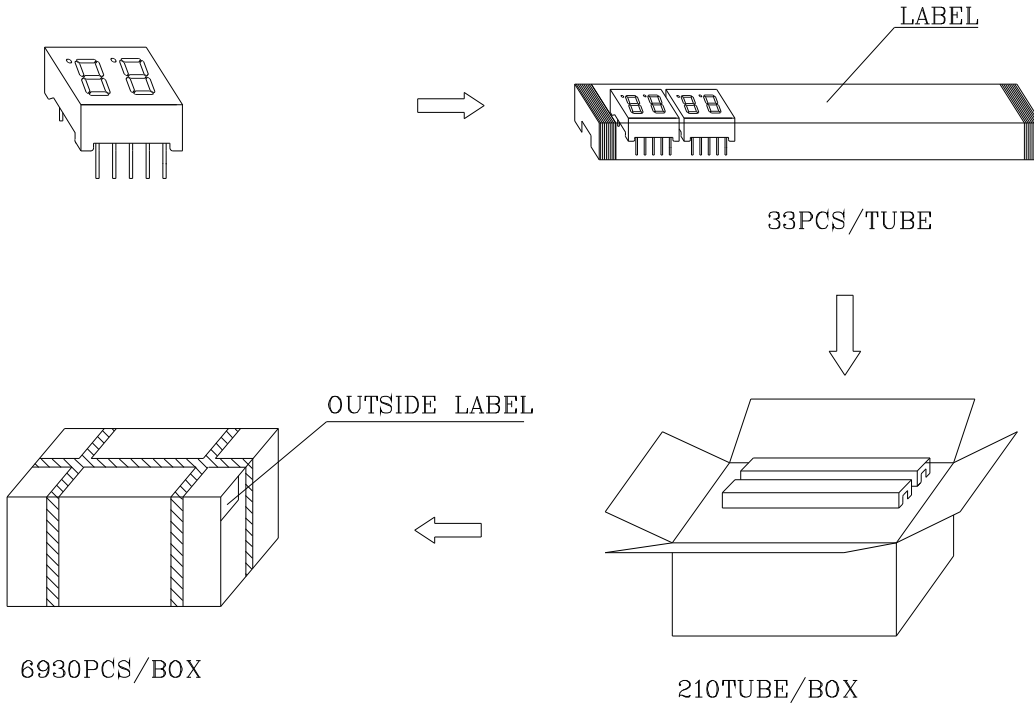
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

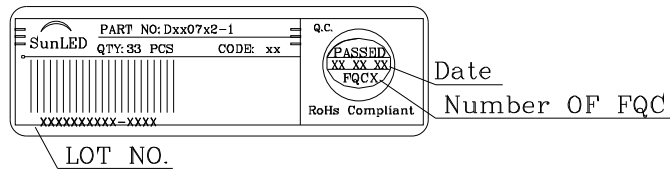
Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

**DUG07A2-1**



Inside LABEL Paste On The IC-tube



Outside LABEL Paste On The Box

